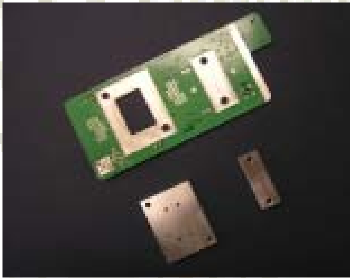
THICK METAL CLAD MICROWAVE CIRCUIT SOLUTIONS FOR HIGH RELIABILITY APPLICATIONS



- Eliminate thermal expansion mismatch issues
  - *warpage - substrate and heatsink*
  - *reliability - components and heastink*
- Reduce weight by 5 to 30% over 6061 aluminum
- Cost effective alternative to pre-bonded materials
- Successfully deployed in Aerospace, Telecom systems

ROBUST • HIGH VALUE • COST EFFECTIVE
ALTERNATIVE TO PRE-BONDED MATERIALS

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